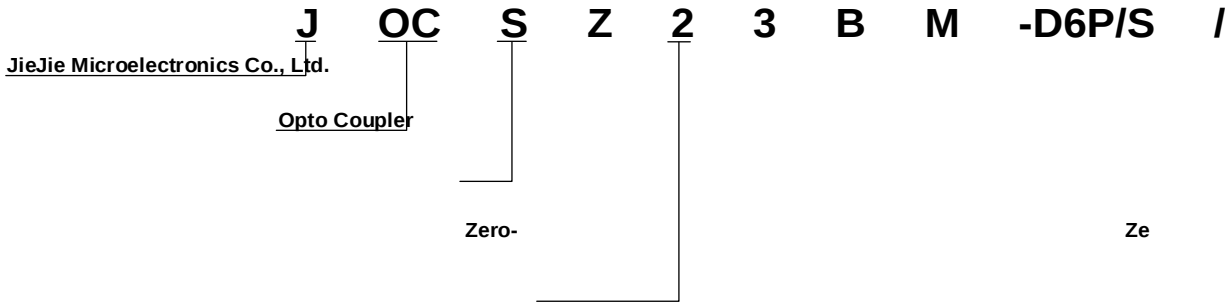


b h £ 9 • σ μ Ἰ ρ α ὤ ς ξ ἦ ς Ω ὸ Υ
 b h £ 9 ! / Û ü o Ψ Ω Ω ἦ ú ς w l

Parameter	Symbol	Condition	Min.	Typ.	. . !
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h w59wLbD LbC h wa ! £ L h b



LED

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

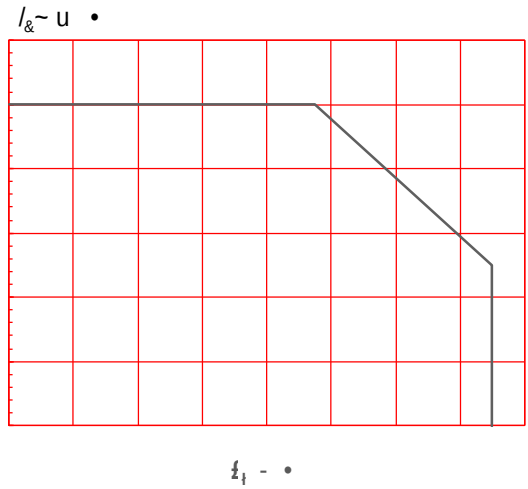


FIG.2: On-state Terminal Current vs. Ambient Temperature

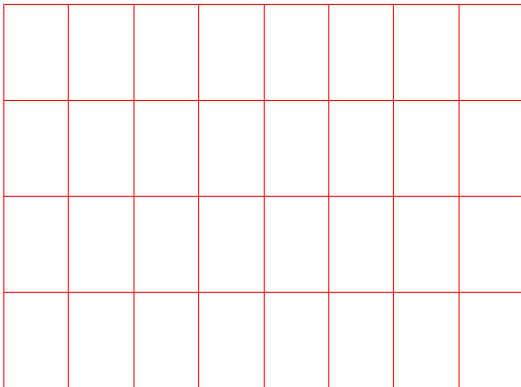


FIG.7: On-state characteristics

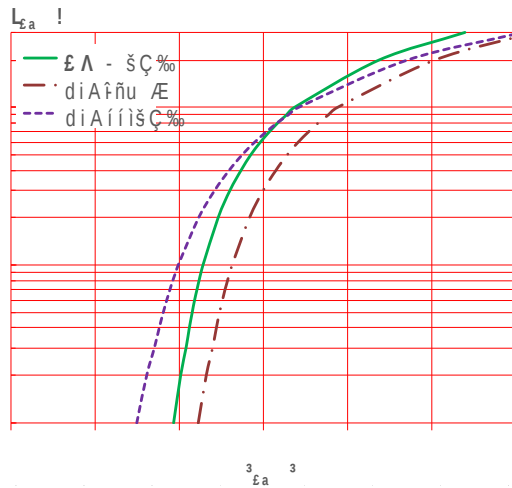


FIG.8: Normalized Holding Current vs. Ambient Temperature

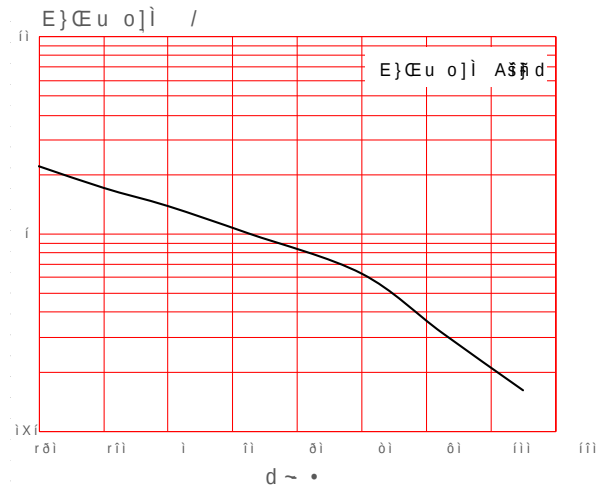


FIG.9: Turn On Time vs. Forward Current

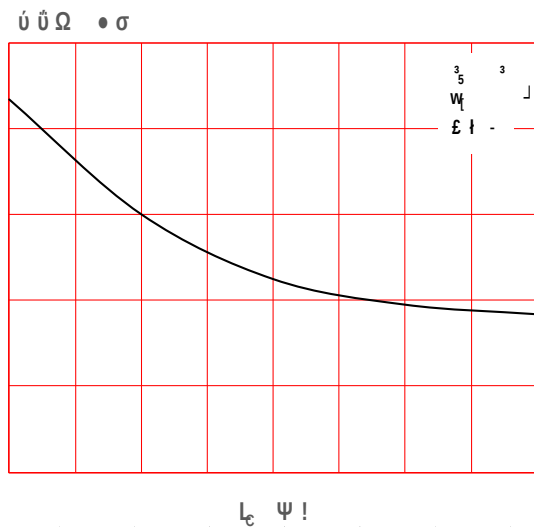
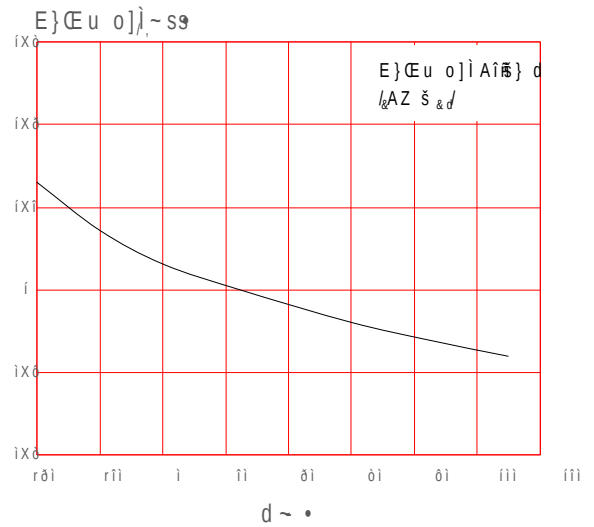


FIG.10: Normalized Inhibit Voltage vs. Ambient Temperature



£ 9 { £ /Lw/ § L £ {

FIG.11: Test Circuits of Turn On Time

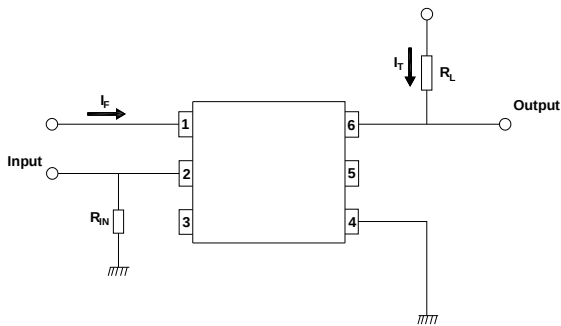


FIG.12: Wave forms of Turn On Time

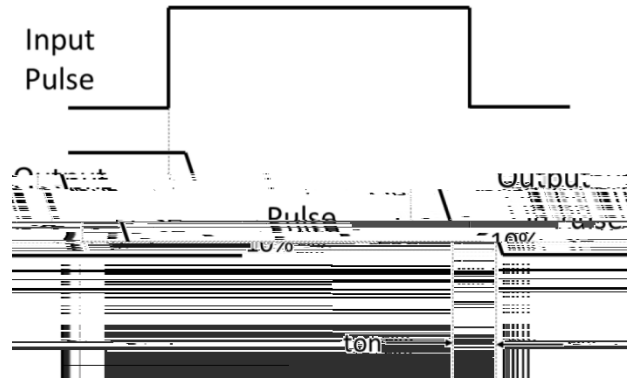
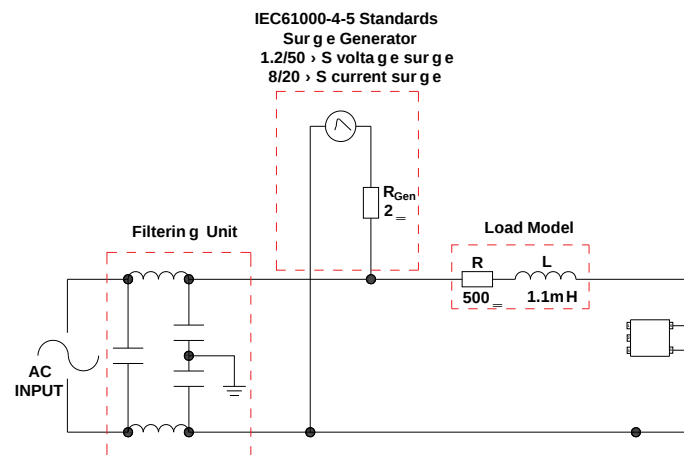
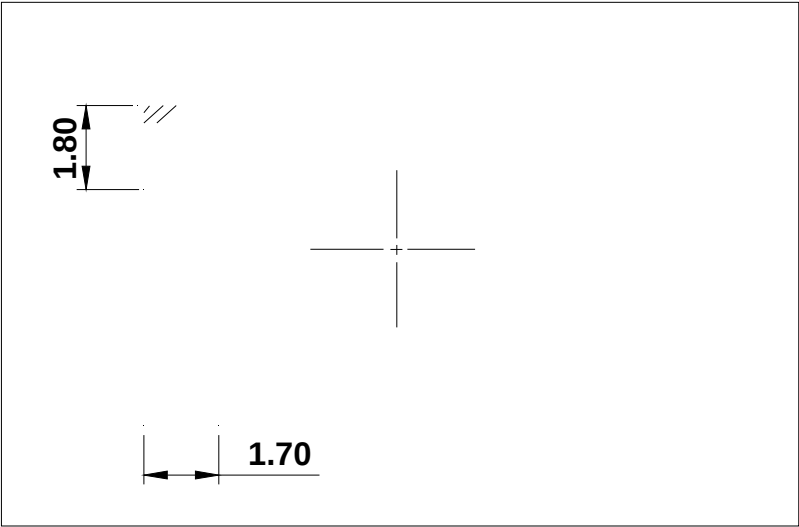


FIG.13: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



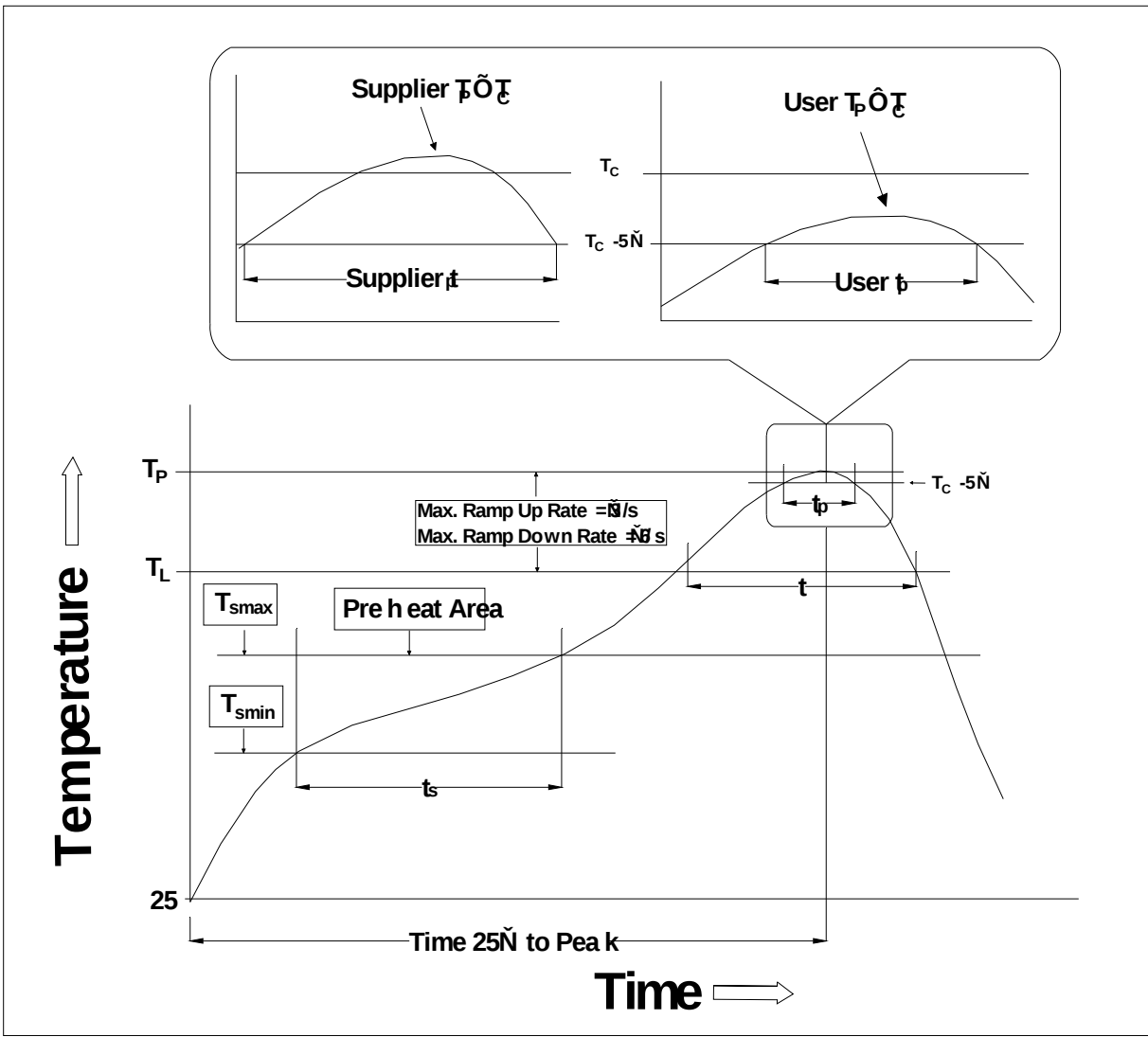
w9/ h aa9b595 { h [59w a ! { Y 5ΩΨ\$Ωσ'ΩŮΩσ'ΩΩΨ\$ΩP\$σσŮ

Option SMD



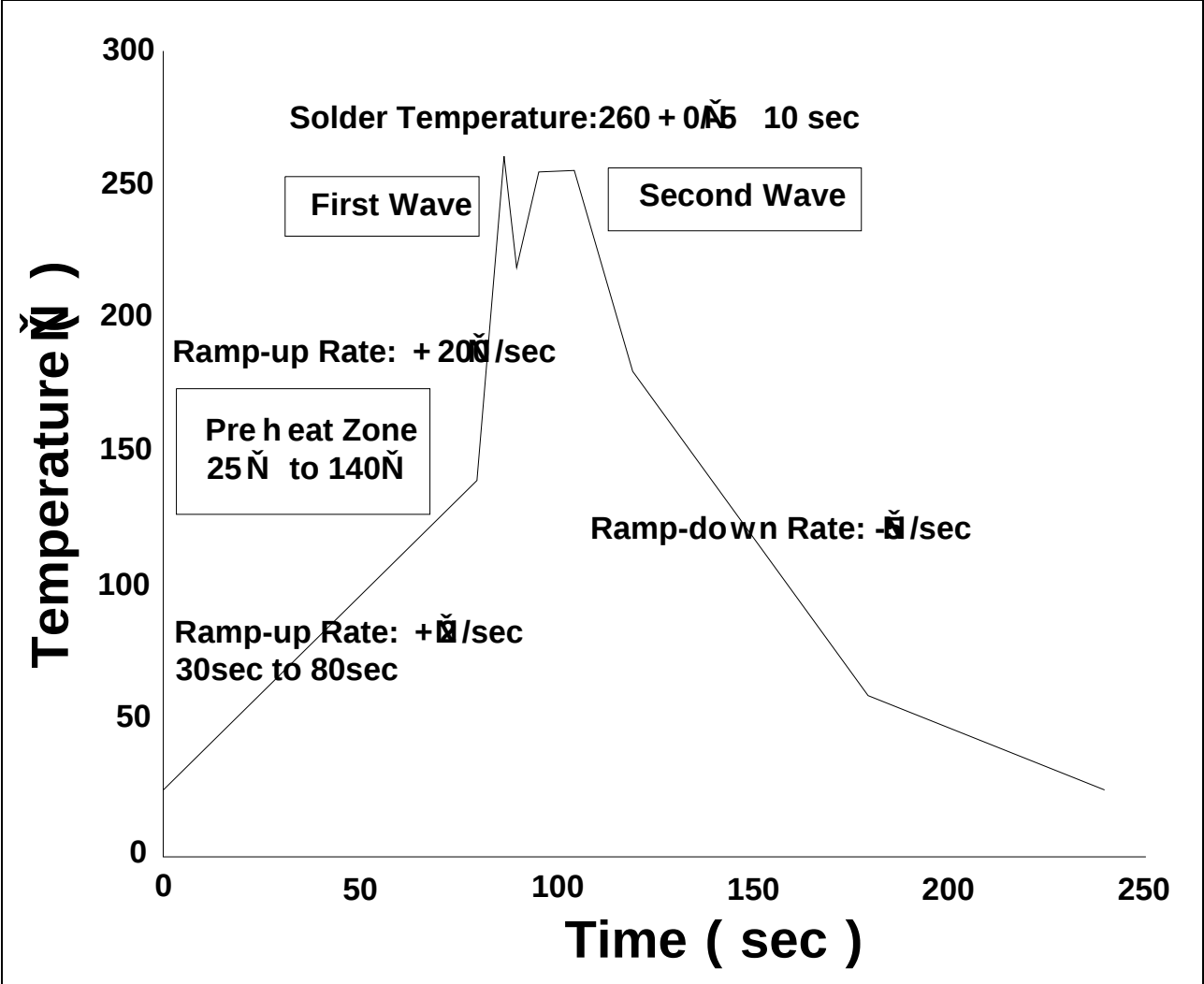
JOC SZ23BM

w9C [h ´ LbCh wa ! £ L h b



Temperature Min. (T_{smin})	150 °C
Temperature Max. (T_{smax})	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 °C/second max.
Liquidus Temperature (T_L)	217 °C
Time (t_L) Maintained Above (T_L)	60-120 seconds
Peak Body Package Temperature	260 °C + 0 °C/-5 °C
Time (t_P) with T_P at 260 °C	10 seconds
Ramp-down Rate (T_P to T_L)	6 °C/second max.

1. 3.9 { h [59wLbD



1. 3.9 { h [59wLbD . ° { h [59wLbD Lw h b	
Soldering Temperature	360 ± 5°C
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and time, no more than three times.
2. Avoid direct contact between the epoxy body